

MSB10120G1

Automotive1200V Silicon Carbide Diode

Features

- 1200-Volt Schottky Rectifier
- Shorter recovery time
- High-speed switching possible
- High-Frequency Operation
- Temperature-Independent Switching Behavior
- Extremely Fast Switching
- Positive Temperature Coefficient on VF

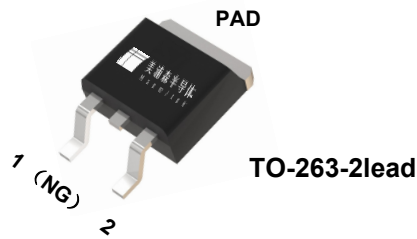
Benefits

- Higher safety margin against overvoltage
- Improved efficiency all load conditions
- Increased efficiency compared to Silicon Diode alternatives
- Reduction of Heat Sink Requirements
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses

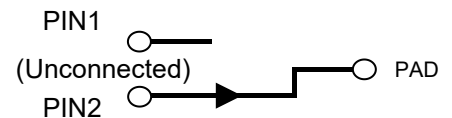
Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor Drives
- HID Lighting

Package



Type : TO-263-2L PAD、Cathode
2、Anode



Absolute Maximum Ratings

$T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	MSB10120G1	Units
VRRM	Repetitive Peak Reverse Voltage	1200	V
VRSM	Surge Peak Reverse Voltage	1200	V
VDC	DC Blocking Voltage	1200	V
IF	Continuous Forward Current @ $T_C=25^{\circ}C$ @ $T_C=135^{\circ}C$ @ $T_C=150^{\circ}C$	29 16 10	A
IFRM	Repetitive Peak Forward Surge Current @ $T_C=25^{\circ}C$, $t_p = 10$ ms, Half Sine Wave	50	A
IFSM	Non-Repetitive Peak Forward Surge Current @ $T_C=25^{\circ}C$, $t_p = 10$ ms, Half Sine Wave	70	A
IF-MAX	Non-Repetitive Peak Forward Surge Current @ $T_C=25^{\circ}C$, $t_p = 10$ us, Plus	600	A
Ptot	Power Dissipation @ $T_C=25^{\circ}C$ @ $T_C=110^{\circ}C$	205 90	W
TJ , Tstg	Operating Junction and Storage Temperature	-55 to +175	$^{\circ}C$

Package Marking

Part Number	Top Marking	Package	Packing Method	MOQ	QTY
MSB10120G1	MSB10120G1	T0-263	Tape	800	4000

Electrical Characteristics

$T_C = 25^\circ \text{C}$ unless otherwise noted

Symbol	Test Conditions	Test Conditions	Min	Typ	Max	Unit
VF	Forward Voltage	IF=10A, TC=25° C IF=10A, TC=175° C	-	1.5 2.2	1.8 3.0	V
IR	Reverse Current	VR=1200V, TC=25° C VR=1200V, TC=175° C	-	2 20	20 100	μA
QC	Total Capacitive Charge	VR=600V, IF=5A TJ=25° C Qc=	-	50	-	nC
C	Total Capacitance	VR=0V, TJ=25° C, f=1MHz VR=400V, TJ=25° C, f=1MHz VR=800V, TJ=25° C, f=1MHz	-	610 46 36	-	pF
EC	Capacitance Stored Energy	VR=800V	-	23.8	-	μJ

Thermal Characteristics

Symbol	Parameter	Typ	Unit
RθJC	Thermal Resistance from Junction to Case	0.73	°C/W

Typical Characteristics

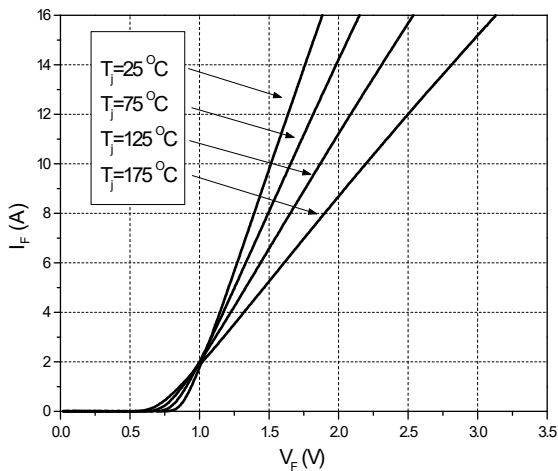


Figure 1. Forward Characteristics

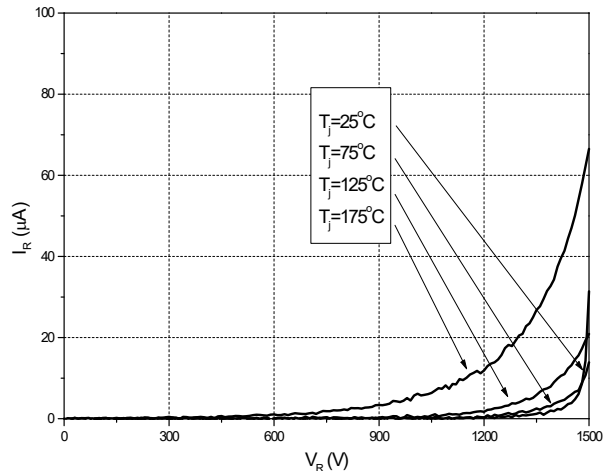


Figure 2. Reverse Characteristics

Typical Characteristics

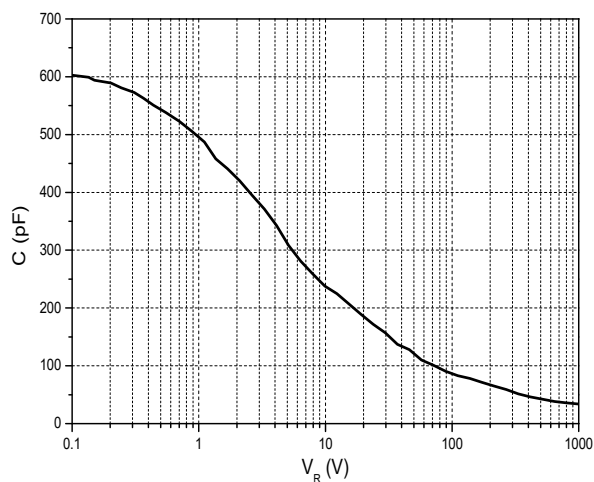


Figure 3. Capacitance vs. Reverse Voltage

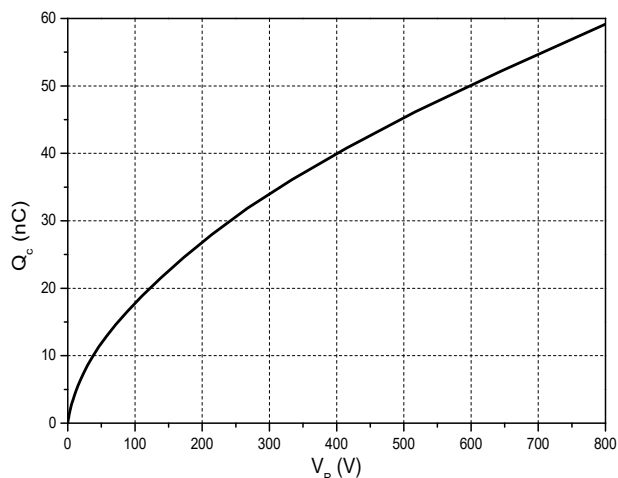


Figure 4. Total Capacitance Charge vs. Reverse Voltage

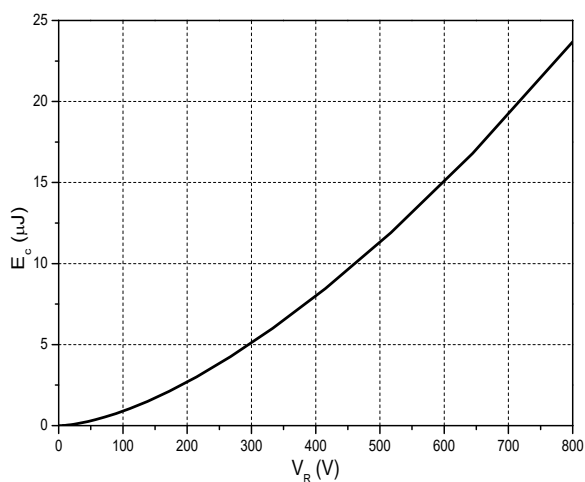


Figure 5. Capacitance Stored Energy

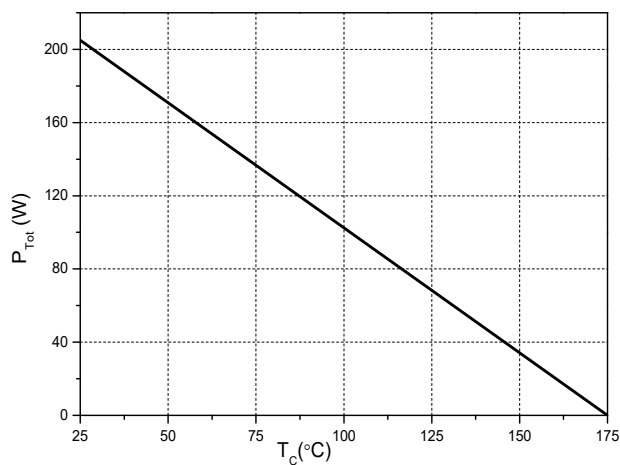


Figure 6. Power Derating

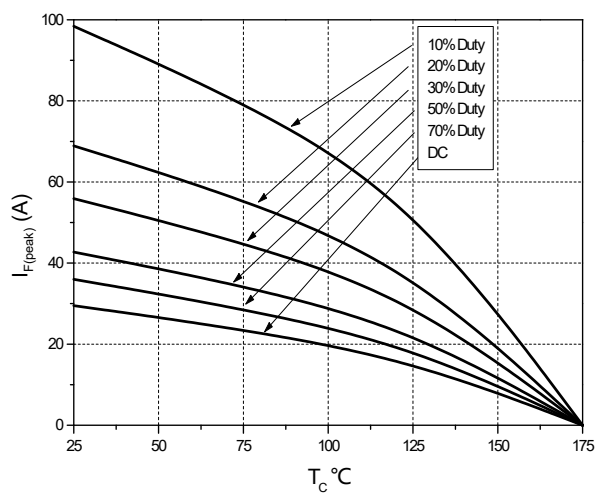


Figure 7. Current Derating

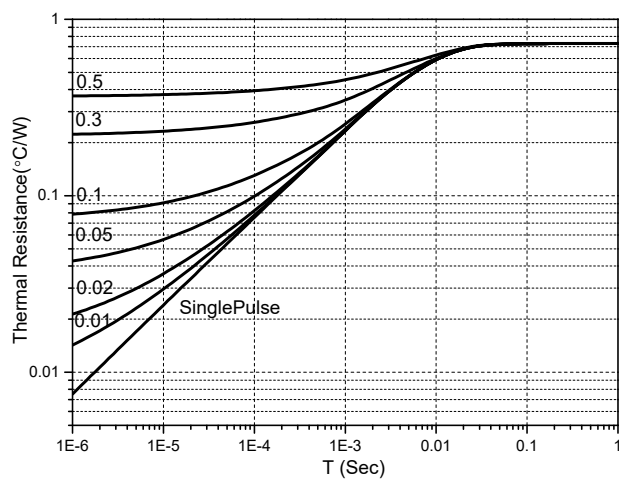
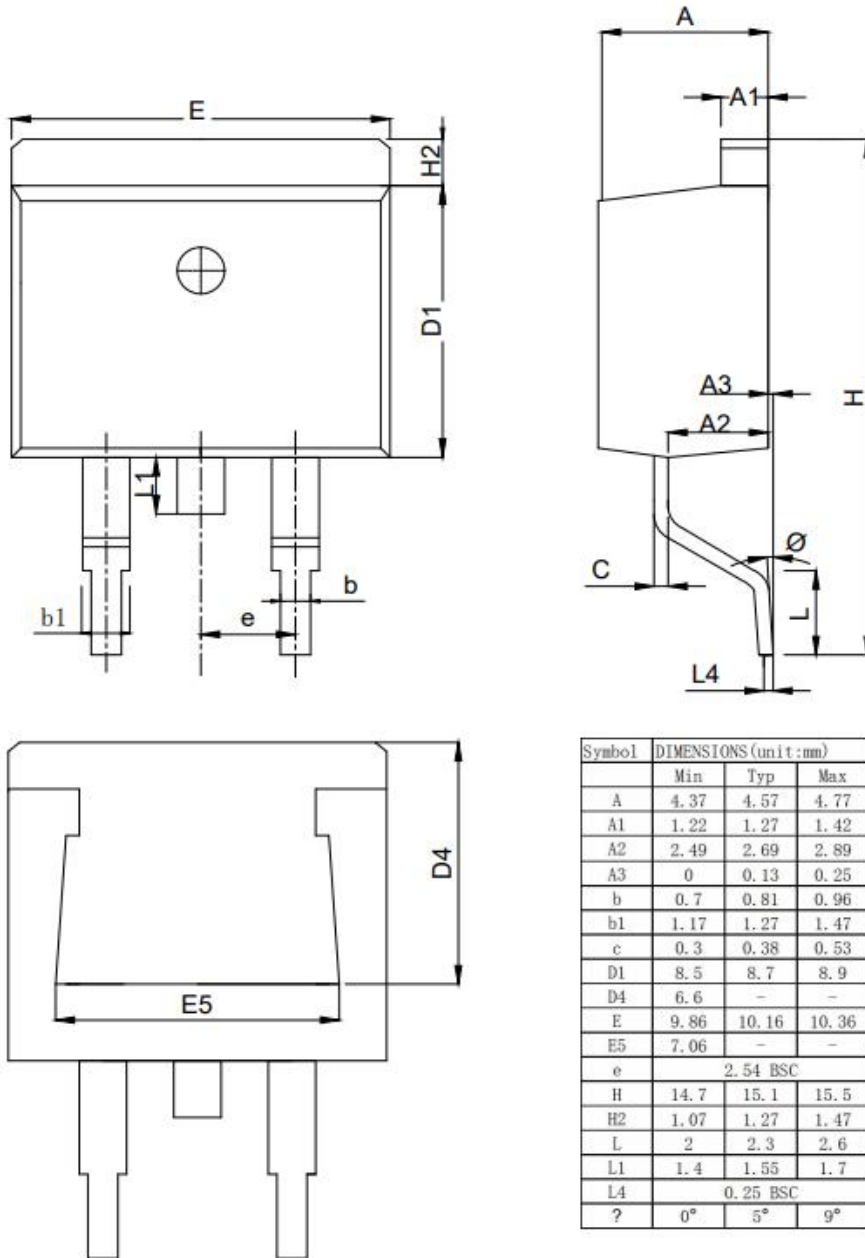


Figure 8. Transient Thermal Impedance

TO-263 OUTLINE



NOTE:

1The plastic package is not marked as smooth surfaceRa=0.1;Subglossy surfaceRa=0.8

2.Undeclared tolerance ± 0.25 ,Unmarked filletRmax=0.25

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